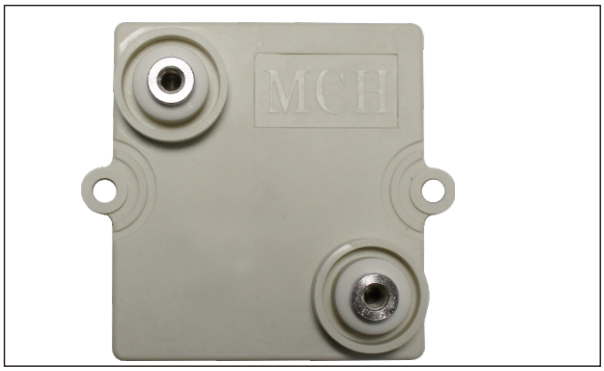
MCH600 Power Thick Film Resistorr



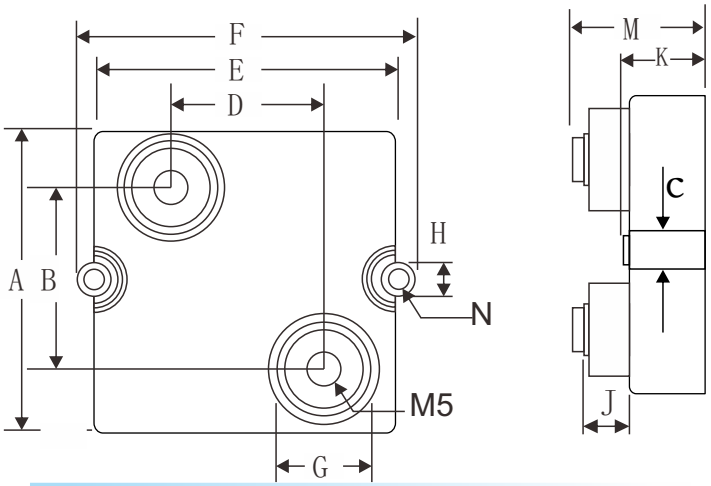
Features

Ⅰ Non-inductive, wide resistance range
Ⅱ High power(the temp of floor center less than 85℃, the power is 600W)
Ⅲ Resistance range: from 0.5Ω to 1MΩ
Ⅳ Small volume, easy mounting
Ⅴ High voltage withstanding 6KV
Ⅵ Insulated case to Ul94 -V0
Ⅶ The thermal resistance 0.115℃/W

Application

Wind power generation, power transmission, robot, frequency converter, switching power supply and so on.

Dimensions



Dimensions			
A	60.3±1.0	G	19.5±0.5
B	36.0±0.5	H	7.50±0.5
C	9.50±0.5	J	9.00±0.5
D	34.0±0.5	K	15.2±0.5
E	57.0±0.5	M	29.0±0.5
F	66.0±1.0	N	4.30±0.5

Applications And Ratings

Type	Rating Power (85℃)	Resistance Range (Ω)	TCR	Precision	Max working Voltage	Working temperature
MCH	600W	0.5Ω—10MΩ	±150PPM/℃	J±5% K±10%	5KV	-55℃~+155℃

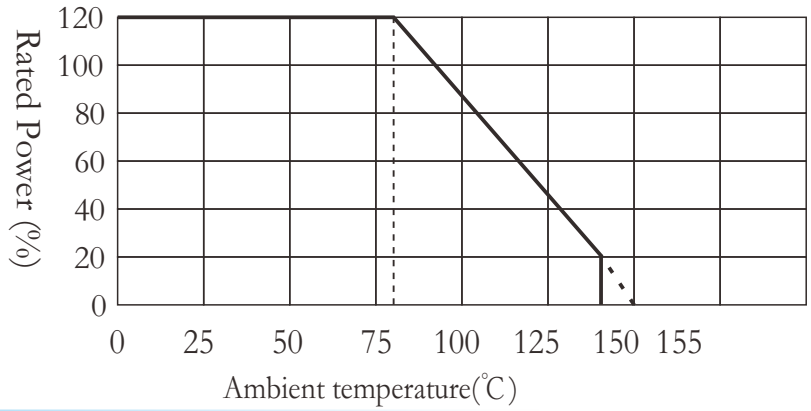
Ordering Information

Example:

MCH	600	J	R100	C
(1)	(2)	(3)	(4)	(5)
Series Name	Power Rating	Resistance Tolerance	Resistance	T.C.R

(1)Type: MCH SERIES
(2)Power Rating: 600=600W
(3)Tolerance: J=±5%,K=±10%
(4)Resistance Value:R100=0.1Ω
(5)T.C.R:C=150PPM/℃

Derating Curve



Resistor Assembly

a. You need to use the thermal conductive silicone between the bottom of the resistor and radiator mounted part, so that it can increase the contact surface, increase the heat dissipation effect.
b. Thermal conductivity silica gel in the preservation will produce precipitation, you muststir well before every usage, and glue roller (market available) it over and over again.
c. You need ensure that no grainy surface impurities. Such as resistor reinstall, must clean the old glue.
d. Before the resistor cover fastening screws, you had better press the positive of the resistor, by rubbing repeatedly several times, make the thermal conductive silicone evenlydistributed, then tighten the screw

Notes

1.Power above 300W can be used in water cooling:
2.Power above 200W can be used in forced air cooling
3.Installation of all the powers of resistors should use thermally conductive silicone rubber on the binding site. The plate of system radiator should be smooth surface.Take MCH600 for example. surface finish should be above 0.05mm, rough surface should be above 6.4um.All the specifications of high voltage resisto r is based on the principle of reduced power curve, X axle is the ambient temperature.

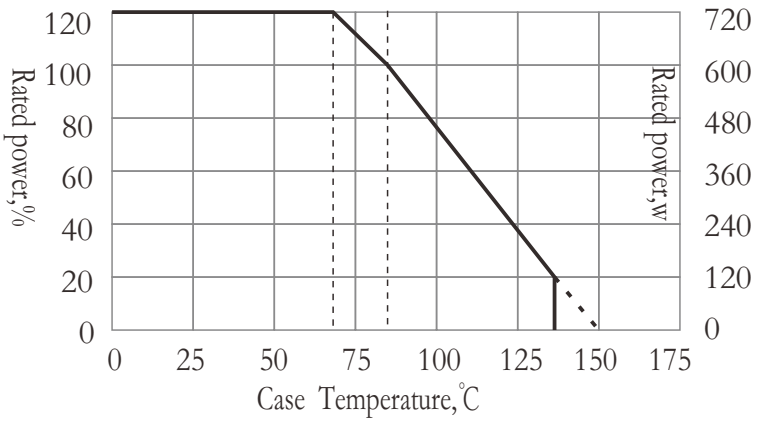
Performance

Test Items	Specifications	Test Methods(JIS C 5201-1)
Moisture resistance	ΔR≤±(0.25%R + 0.001Ω).	56 days/40℃,RH≥95%
Thermal cycling	ΔR≤±(0.2%R + 0.001Ω).	-55° C/+125° C(0.5h each), 5 cycles
Vibration, high frequency	ΔR ≤±(0.2%R+ 0.001Ω).	MIL－Std－202, method 204, Cond.D
Load life	ΔR≤±(0.4%R+ 0.001Ω).	1,000 hours at rated power, BCT=85℃
Short time overload	ΔR≤±(0.4%R + 0.001Ω).	1000W,70° C,10 S
Peak current	up to 1500Amp. Depending on pulse length and frequency.	
Dielectric strength	6KVrms,50Hz,1min,12KVrms on request.	
Partial discharge	4KVrms,<10pC;7KVrms on request.	
Insulation resistance	10GΩ, Min at 500V.	
Creeping distance:	42mm, Min.	
Air distance	14mm, Min.	
Inductance	≤80nH	
Capacitance /Mass	≤110pF	
Capacitance /Parallel	≤40pF	
Contact terminal	M5 screw, Max torque 2Nm	
Resistor installation	M4 screw, Max torque 1.8Nm	

Requirements For System Heat Dissipation

For different kinds of power resistors, a common design is that they all have a cooling plate on the bottom of the shape, users use spare screw to fix on the system radiator, so that it can peel off the heat which is produced in the process of the working of resistors and then the heat can achieve a balance. Balance temperature (TO) of the centre of the electric heater plate is determined by the thermal performance of the system. Higher the thermal performance, Lower the TO.

Power resistors only have the design of fix assembly (cooling plate, fixed screw) , system radiator is designed by the users self. Generally manufacturers can not provide the detail requirements of the system designed by the users self. Generally manufacturers can not provide the detail requirements of the system radiator. Because it is a multiple parameters, such as environment (temperature, ventilation), the shape of radiator, wind speed (or water carrying capacity , water temperature), whether the radiator can work together with other power components, so we can not provide. Users themselves can not only depend on the parameters of the resistors to predict the temperature rise when working either. Because they are depended on the working situation of the users, the only thing manufacturer can provide is the "reduced power curve". Take MCH 600for example as below picture.



Y axle: the rated power allowed.

X axle: the balance temperature of the corresponding centre position of the bottom plate of the resistor,

The curve is the result of the design of a comprehensive confirmation curve (or binding curve). Rather than referring to the relationship between the temperature and power of the resistor under any specific work condition. But it is very useful, practical work process is:

1: Users can install according to the experience and practical situation to design the radiator.

2: Users can add the expected power load to the resistor.

3: The temperature of the centre position of the bottom plate of the resistor after thermal equilibrium, if this temperature is comply to " temperature≤corresponding curve X Coordinates numerical (Y axle is the power added practically), it means this system is suited to install, you can improve the cooling situation or low down the actually power.

We provide "Reduced power slope and Thermal resistance" behind the Reduced power curve, Take MCB600for example as below::

1.Reduced power slope: 8.73W/℃ which is the rectilinear slope of the curve from 85℃ to 140℃(480W/55℃) .

2. Thermal resistance: 0.115℃/W is the reciprocal of the slope as descript above.Noted:

The thermal resistance could not be understood for the Inherent characteristic parameters of the resistors under free conditions (without external radiator)It isfrom "Reduced power slope" and it is only the description of reduced power. As for the comprehensive nature of the reduced power itself, so the thermal resistance we talked above is not a description of relationship between temperature and power under any conditions.